

TSM2N70CZ C0-VB Datasheet

Power MOSFET

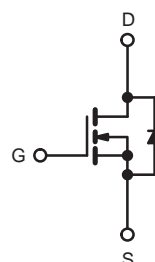
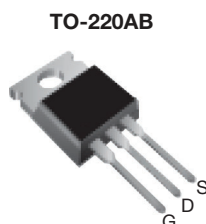
PRODUCT SUMMARY		
V _{DS} (V)	700	
R _{DS(on)} (Ω)	V _{GS} = 10 V	2.7
Q _g (Max.) (nC)	48	
Q _{gs} (nC)	12	
Q _{gd} (nC)	19	
Configuration	Single	

FEATURES

- Low Gate Charge Q_g Results in Simple Drive Requirement
- Improved Gate, Avalanche and Dynamic dV/dt Ruggedness
- Fully Characterized Capacitance and Avalanche Voltage and Current
- Compliant to RoHS directive 2002/95/EC



RoHS*
COMPLIANT




N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T _C = 25 °C, unless otherwise noted			
PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V _{DS}	700	V
Gate-Source Voltage	V _{GS}	± 30	
Continuous Drain Current ^e	V _{GS} at 10 V	T _C = 25 °C	A
Continuous Drain Current		T _C = 100 °C	
Pulsed Drain Current ^a	I _{DM}	18	
Linear Derating Factor		0.48	W/°C
Single Pulse Avalanche Energy ^b	E _{AS}	325	mJ
Repetitive Avalanche Current ^a	I _{AR}	4	A
Repetitive Avalanche Energy ^a	E _{AR}	6	mJ
Maximum Power Dissipation	P _D	60	W
Peak Diode Recovery dV/dt ^c	dV/dt	2.8	V/ns
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to + 150	°C
Soldering Recommendations (Peak Temperature) ^d	for 10 s	300	
Mounting Torque	6-32 or M3 screw		lbf · in
			N · m

Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- Starting T_J = 25 °C, L = 24 mH, R_G = 25 Ω, I_{AS} = 3.2 A (see fig. 12).
- I_{SD} ≤ 3.2 A, dI/dt ≤ 90 A/μs, V_{DD} ≤ V_{DS}, T_J ≤ 150 °C.
- 1.6 mm from case.
- Drain current limited by maximum junction temperature.

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	65	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	-	2.1	

SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$		700	-	-	V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^\circ\text{C}$, $I_D = 1\text{ mA}^d$		-	670	-	mV/°C
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$		2.0	-	4.0	V
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 30\text{ V}$		-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 700\text{ V}, V_{GS} = 0\text{ V}$		-	-	25	μA
		$V_{DS} = 560\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$		-	-	250	
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$	$I_D = 3.1\text{ A}^b$	-	2.7	-	Ω
Forward Transconductance	g_{fs}	$V_{DS} = 50\text{ V}, I_D = 3.1\text{ A}$		3.9	-	-	S
Dynamic							
Input Capacitance	C_{iss}	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1.0\text{ MHz}$, see fig. 5		-	1417	-	pF
Output Capacitance	C_{oss}			-	177	-	
Reverse Transfer Capacitance	C_{rss}			-	7.0	-	
Output Capacitance	C_{oss}	$V_{GS} = 0\text{ V}$	$V_{DS} = 1.0\text{ V}, f = 1.0\text{ MHz}$	-	1912	-	pF
			$V_{DS} = 560\text{ V}, f = 1.0\text{ MHz}$	-	48	-	
Effective Output Capacitance	$C_{oss\text{ eff.}}$	$V_{DS} = 0\text{ V to } 560\text{ V}^c$		-	84	-	
Total Gate Charge	Q_g	$V_{GS} = 10\text{ V}$	$I_D = 3.2\text{ A}, V_{DS} = 400\text{ V}$ see fig. 6 and 13 ^b	-	-	48	nC
Gate-Source Charge	Q_{gs}			-	-	12	
Gate-Drain Charge	Q_{gd}			-	-	19	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 325\text{ V}, I_D = 3.2\text{ A}$ $R_G = 9.1\text{ }\Omega, R_D = 62\text{ }\Omega$, see fig. 10 ^b		-	14	-	ns
Rise Time	t_r			-	20	-	
Turn-Off Delay Time	$t_{d(off)}$			-	34	-	
Fall Time	t_f			-	18	-	
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode 	-	-	4	A	
Pulsed Diode Forward Current ^a	I_{SM}		-	-	21		
Body Diode Voltage	V_{SD}	$T_J = 25\text{ }^\circ\text{C}, I_S = 3.2\text{ A}, V_{GS} = 0\text{ V}^b$		-	-	1.5	V
Body Diode Reverse Recovery Time	t_{rr}	$T_J = 25\text{ }^\circ\text{C}, I_F = 3.2\text{ A}, di/dt = 100\text{ A}/\mu\text{s}^b$		-	493	739	ns
Body Diode Reverse Recovery Charge	Q_{rr}			-	2.1	3.2	μC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)					

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width $\leq 300\text{ }\mu\text{s}$; duty cycle $\leq 2\%$.
- c. $C_{oss\text{ eff.}}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} .
- d. $t = 60\text{ s}, f = 60\text{ Hz}$.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Fig. 1 - Typical Output Characteristics



Fig. 3 - Typical Transfer Characteristics

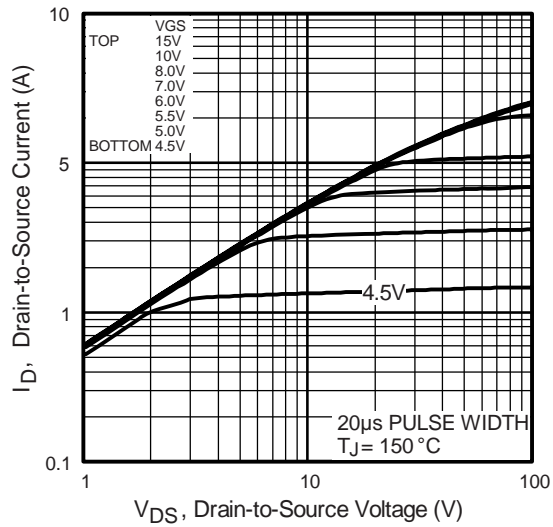


Fig. 2 - Typical Output Characteristics

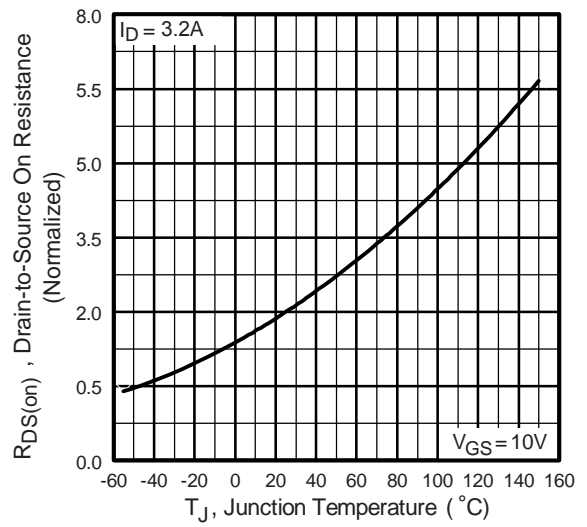


Fig. 4 - Normalized On-Resistance vs. Temperature

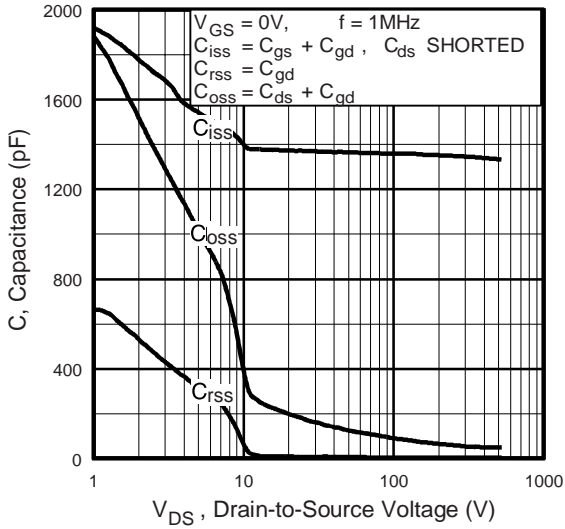


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

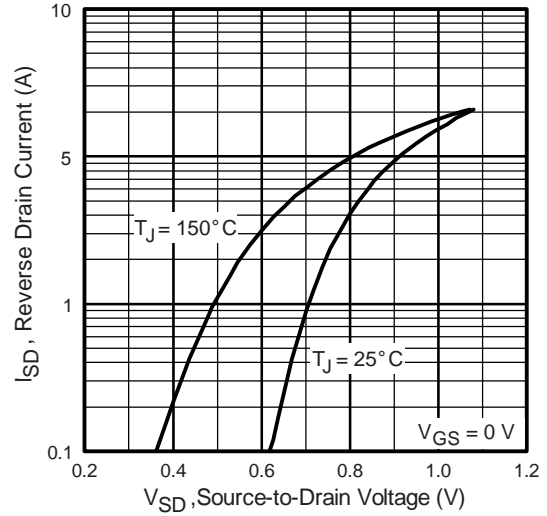


Fig. 7 - Typical Source-Drain Diode Forward Voltage

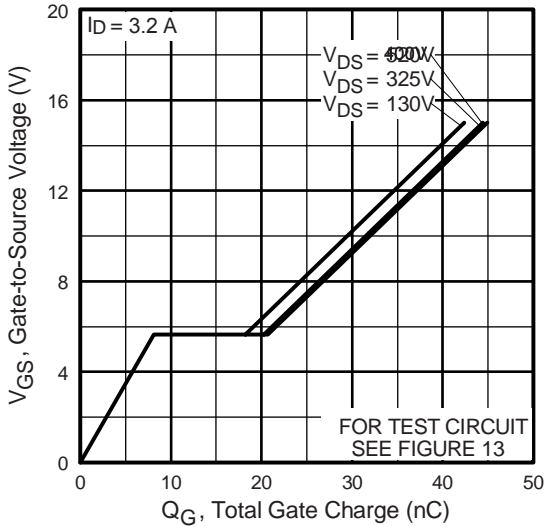


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

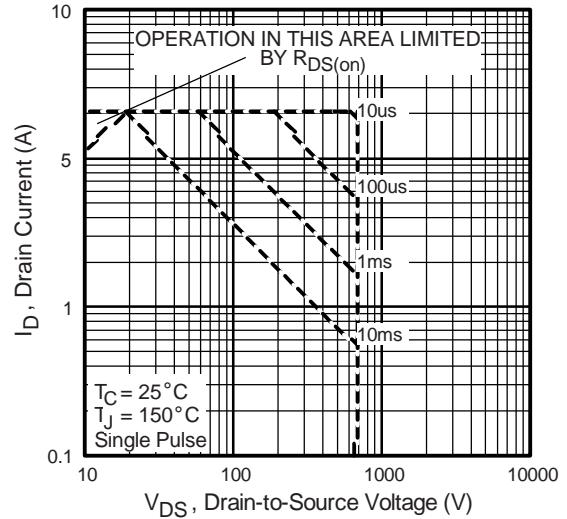


Fig. 8 - Maximum Safe Operating Area



Fig. 9 - Maximum Drain Current vs. Case Temperature



Fig. 10a - Switching Time Test Circuit

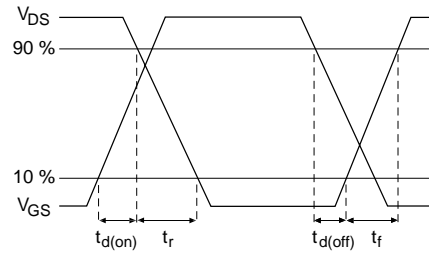


Fig. 10b - Switching Time Waveforms

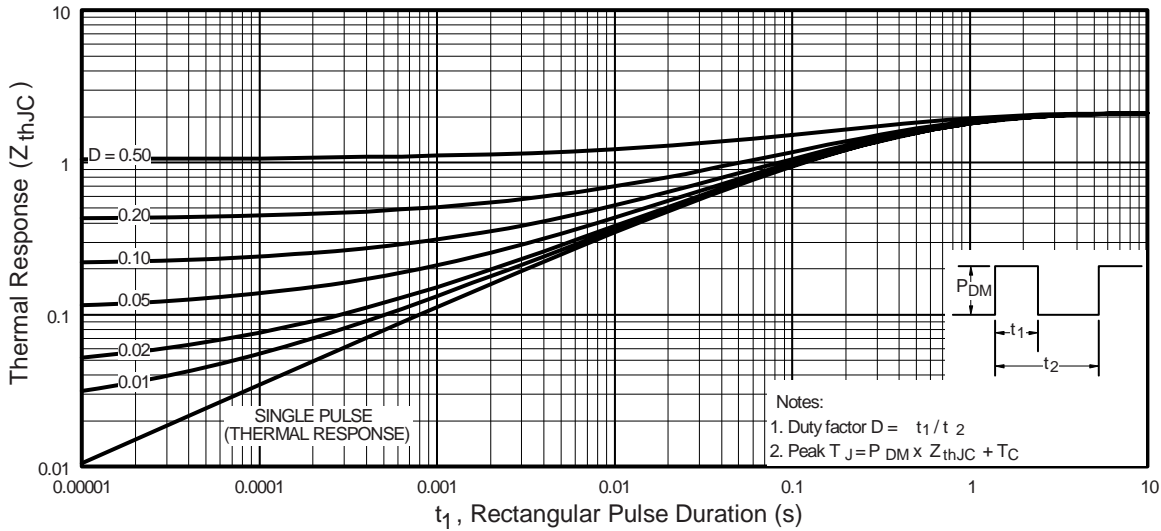


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

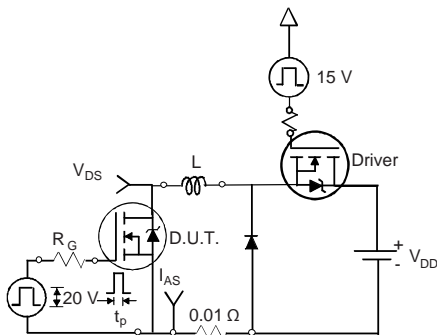


Fig. 12a - Unclamped Inductive Test Circuit

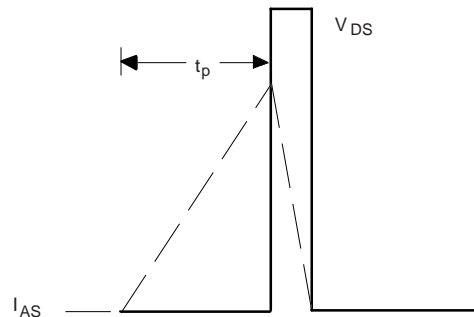


Fig. 12b - Unclamped Inductive Waveforms

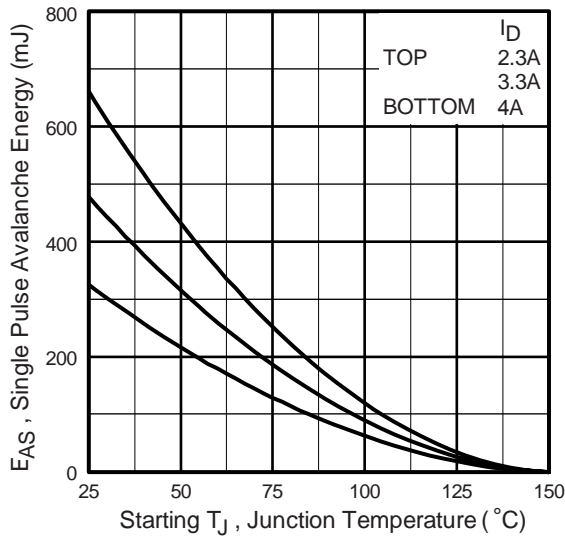


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

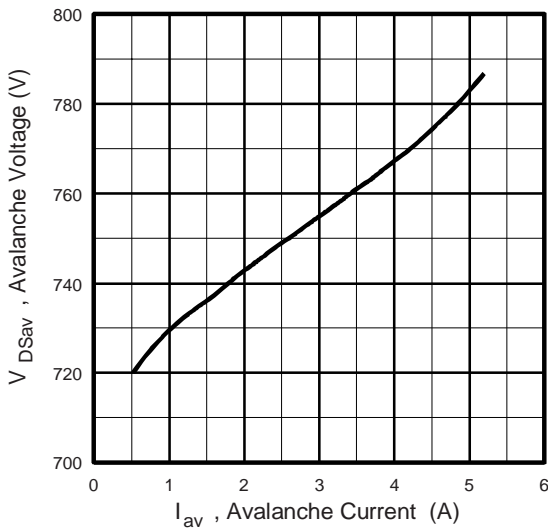


Fig. 12d - Typical Drain-to Source Voltage vs. Avalanche Current

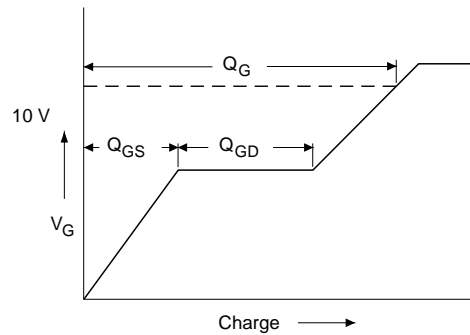


Fig. 13a - Basic Gate Charge Waveform



Fig. 13b - Gate Charge Test Circuit

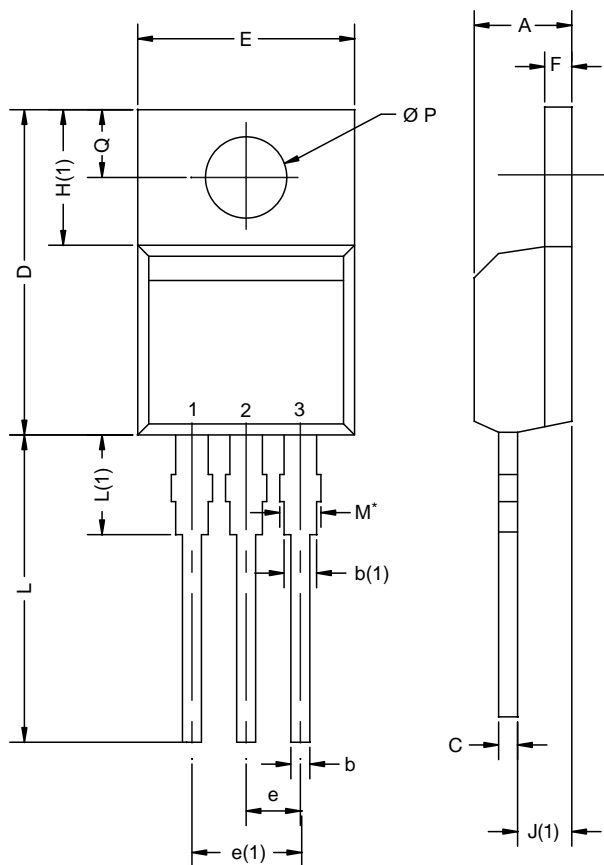
Peak Diode Recovery dV/dt Test Circuit



* $V_{GS} = 5 V$ for logic level devices

Fig. 14 - For N-Channel

TO-220AB



DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.25	4.65	0.167	0.183
b	0.69	1.01	0.027	0.040
b(1)	1.20	1.73	0.047	0.068
c	0.36	0.61	0.014	0.024
D	14.85	15.49	0.585	0.610
E	10.04	10.51	0.395	0.414
e	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.09	6.48	0.240	0.255
J(1)	2.41	2.92	0.095	0.115
L	13.35	14.02	0.526	0.552
L(1)	3.32	3.82	0.131	0.150
Ø P	3.54	3.94	0.139	0.155
Q	2.60	3.00	0.102	0.118

ECN: X12-0208-Rev. N, 08-Oct-12
DWG: 5471

Notes

* M = 1.32 mm to 1.62 mm (dimension including protrusion)
Heatsink hole for HVM

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